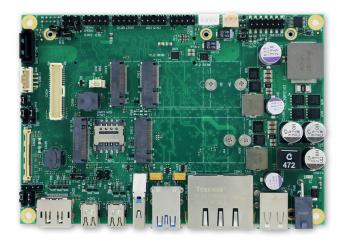
COM EXPRESS®

Carrier-COMe-T6-C30

Carrier Board for COM Express® Type 6 Modules on 3.5" form factor

Most compact, I/O-rich COM Express® Type 6 carrier board



HIGHLIGHTS

- $\cdot\,$ Specifically designed for digital signage
- · Broad variety of connectivity possibilities in the compact 3.5" form factor
- · Multi-display support
- · Ultimate versatility



FEATURES

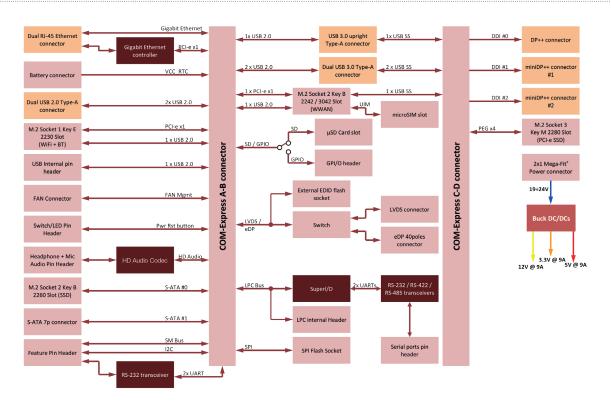
Video Interfaces	1 x DP++ connector 2 x miniDP++ connectors LVDS 24-bit Single/Dual Channel LVDS External EDID flash socket eDP 4-lanes 40 poles VESA connector
Mass Storage	S-ATA 7p M connector + 4 pins power connector M.2 Socket 2 2260 Key B slot for SSD M.2 Socket 3 2280 Key M slot for PCI-e x4 SSDs µSD Card slot (interface multiplexed with GPIO header)
로마 Networking	Dual RJ-45 connector (1 port managed by COM Express Gigabit Ethernet interface, 1 port managed by Carrier board's Intel® (21x GbEthernet controller) M.2 Socket 2 2242 / 3042 Key B slot for WWAN modules (modem) M.2 Socket 1 2230 Key E slot for WiFi / BT modules
•<→ USB	3 x USB 3.0 Host ports on Type-A sockets 2 x USB 2.0 Host ports on Type-A sockets 1 x USB 2.0 Host port on internal pin header
Audio	On-board HD Audio Codec (Realtek ALC262) Mic In + Line Out internal pin header
Serial Ports	2 x RS-232 / RS-422 / RS-485 ports on internal pin header (from carrier board's Superl/O) 2 x RS-232 ports on feature pin header (from module)

	Other Interfaces	microSIM slot for M.2 modem 4 x GPI + 4 x GPO pin header (interface multiplexed with µSD slot) Button / LEDs front panel header 3-pin tachometric FAN connector I2C + SM Bus on feature Pin header LPC internal header
	Power Supply	19÷24 V _{DC} (only CPU modules with max 45W TDP supported) Mega-Fit® 2x1 Power Connector Cabled Coin-cell connector for RTC
[Operating Temperature*	0°C ÷ +50°C
L	Dimensions	146x102mm (3.5" form factor, 5.75" x 4.02")

*All carrier board components must remain within the operating temperature at any and all times, including start-up; carrier operating temperature is independent of the module installed. Please refer to the specific module for more details. Actual temperature will widely depend on application, enclosure and/or environment. Upon customer to consider specific cooling solutions for the final system.



BLOCK DIAGRAM





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DATA ORCHESTRATION

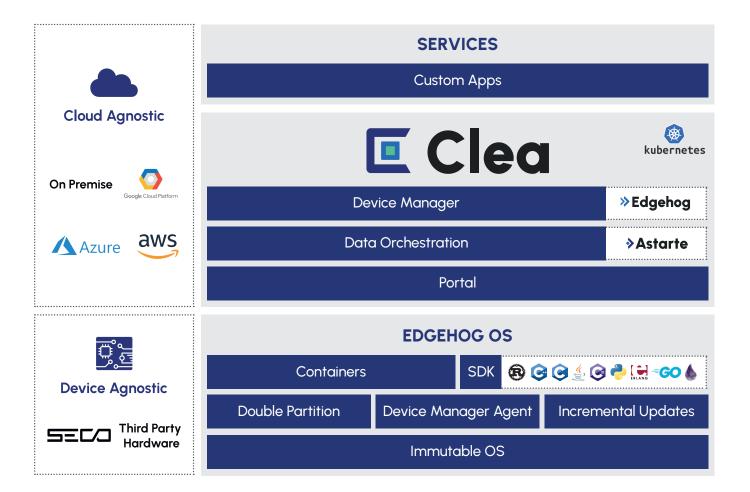
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